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(71) Applicant: **MOTOROLA, INC.** [US/US]; 1303 East Algonquin Road, Schaumburg, IL 60196 (US).

(72) Inventors: **SCHEIFERS, Steven, M.**; 4400 Capstan Drive, Hoffman Estates, IL 60195 (US). **SKIPOR, Andrew**; 592 Partridge Drive, West Chicago, IL 60185 (US). **GAMOTA, Daniel**; 1137 Parkside Drive, Palatine, IL 60067 (US).

(74) Agents: **NICHOLS, Daniel, K.** et al.; Motorola, Inc., Intellectual Property Dept., 1303 East Algonquin Road, Schaumburg, IL 60196 (US).

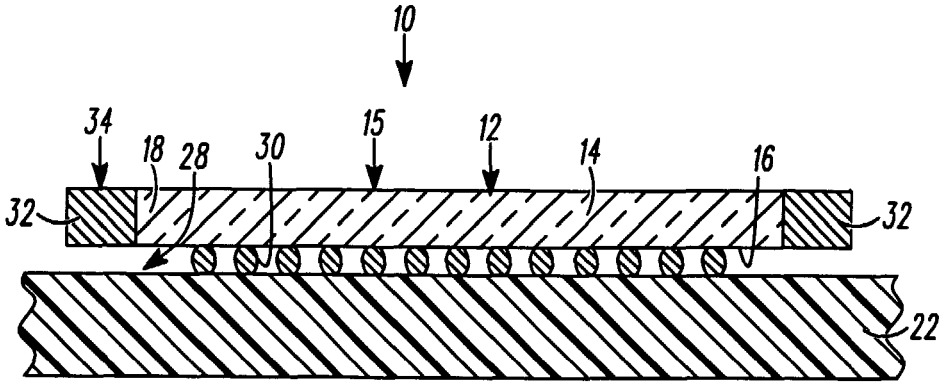
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(54) Title: MICROELECTRONIC ASSEMBLY WITH DIE SUPPORT AND METHOD



(57) Abstract: A microelectronic assembly (6) includes a substrate (22) having a plurality of bond pads disposed on a substantially planar die attach surface and an integrated circuit die (12) having a die face and a plurality of bond pads of the die (12) face. The die is provided with a polymeric bead (32) about the outer edges of the die. Die face bond pads are aligned with corresponding substrate bond pads and electrically interconnected by heating to a reflow temperature. Exposure of the polymeric bead (32) to the reflow temperature causes the bead to form a peripheral bond between the die and the substrate (22).

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